

ENGIS[®] MICROTECH TECHNICAL DATA

P8 POLISHING SLURRY

A COLLOIDAL SILICA POLISHING SLURRY WITH NANO SIZE
NON-CRYSTALLINE SILICA PARTICLES IN AN AQUEOUS BASE .

ACCELERATES CMP EFFECT IN POLISHING
SAPPHIRE, SILICON NITRIDE & OTHER HARD MATERIALS.

PRODUCT DESCRIPTION

- ◆ READY TO USE AFTER MIXING PART A AND PART B AT A 4:1 RATIO
- ◆ ENHANCED CMP EFFECT TO REDUCE PROCESS TIME
- ◆ NO SEPARATION OR CRYSTALLIZATION DURING USE OR SHIPPING
- ◆ NO FREEZING AT 0°C
- ◆ NON FLAMMABLE
- ◆ NO OZONE DEPLETING CHEMICALS
- ◆ NO VOC OR HARMFUL SOLVENTS
- ◆ COMPLETELY ODORLESS
- ◆ PROTECTED AGAINST BACTERIAL AND FUNGUS DETERIORATION
- ◆ EASILY REMOVED WITH WATER
- ◆ FOR BEST RESULTS USE WITHIN 48 HOURS OF MIXING

TECHNICAL DATA

PH:	10 - 11
VISCOSITY:	< 6 cps
MEAN SIZE:	0.060μ
SOLIDS %:	15%
DENSITY:	1.09 g/cm ³

PACKAGING

KIT CONTAINS - BOTH PART A AND PART B

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ADVANCED MATERIALS PRODUCTS



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